



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

13-FEB-2002

SUBJECT: ON Semiconductor Initial Product/Process Change Notification #12287

TITLE: Small Signal Schottky Process Consolidation in Zener Rectifier Wafer Fab

EFFECTIVE DATE: 13-Jun-2002

AFFECTED CHANGE CATEGORY:

**ON Semiconductor Fab Site
Subcontractor Fab Site
Shrink Die**

AFFECTED PRODUCT DIVISION: Bipolar Discretes Products Div

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or Laura Rivers <S20636@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office
or Barbara Matteson <RM2230@onsemi.com>

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact Sales Office or Donald Barlow <R39117@onsemi.com>

DISCLAIMER:

Initial Product/Process Change Notification (IPC�) - First Notification distributed to customers.
Distributed at least 120 days from the effective date of the change.

This is an 'early warning' about an upcoming change and contains general information regarding the change details and devices affected. It also contains at least a reliability qualification plan, but the actual qualification data will be identified in the Final Product/Process Change Notification (FPCN).

This notification will be followed by a Final Product/Process Change Notification (FPCN)
at least 60 days from effective date of change.

DESCRIPTION AND PURPOSE:

ON Semiconductor wishes to notify its Customers that Small Signal Schottky Fabrication located in Primarion Wafer Fab, Tempe, Arizona and ON Semiconductor's Zener/Rectifier Wafer Fab, Phoenix, Arizona will be consolidated into ON Semiconductor's Zener/Rectifier Wafer Fab, Phoenix, Arizona. Some devices will undergo a non-active area die shrink in accordance with current design rules.

**Initial Product/Process Change Notification #12287**

NOTE: Only the following list of parts will be affected by the non active area die shrink.

MMDL101T1
MMBD352WT1
MBD110DWT1
MMBD101LT1
SMBD1015LT1
SMMBD101LT1
MMBD352LT1
SMBD1013LT3
MMBD353LT1
MMBD353LT3
MMBD354LT1
MMBD355LT1
MBD101

QUALIFICATION PLAN:

Reliability study including the following tests:

H3TRB
HTRB
Autoclave
Electrical Distribution
TC
ESD
DPA after H3TRB
IOL
Resistance to Solder Heat
DPA after TC

AFFECTED DEVICE LIST (WITHOUT SPECIALS):**PART**

BAS40-04LT1
BAS40-06LT1
BAS40LT1
BAS70-04LT1
BAS70LT1
BAT54ALT1
BAT54HT1
BAT54LT1
BAT54SLT1
BAT54SWT1
BAT54T1
BAT54WT1
LMCFD301WP
LMCFT54WP
MBD101
MBD110DWT1
MBD301
MBD330DWT1
MBD54DWT1
MBD701
MBD770DWT1
MMBD101LT1
MMBD301LT1

**Initial Product/Process Change Notification #12287**

MMBD301LT3
MMBD330T1
MMBD352LT1
MMBD352WT1
MMBD353LT1
MMBD353LT3
MMBD354LT1
MMBD355LT1
MMBD452LT1
MMBD701LT1
MMBD701LT3
MMBD717LT1
MMBD770T1
MMDL101T1
MMDL301T1
MMDL770T1
MMSD301T1
MMSD701T1
NSR15TW1T2
RB751V40T1
SBAS40-06LT1
SBAT54ALT1
SBAT54SLT1
SMMBD101LT1
SMMBD301LT1
SMMBD301LT3
SMMBD701LT1
SMMBD701LT3